



32Mb PPI MRAM M-die

Parallel Peripheral Interface MRAM

3.3V/1.8V

- **S3R3216V1M**
- **S3R3216R1M**

Datasheet

Feature

- Interface
 - Parallel Asynchronous and Page Mode Interface
- Page Mode Read Access
 - Interpage read access : 70ns
 - Intrapage read access : 15ns
- Page Mode Write Access
 - Interpage write access : 240ns
 - Intrapage write access : 15ns
- Page Size
 - x16 I/O Mode : 4-word page size
- Low Power Consumption
 - Read current(3.3V) : 14mA
 - Write current(3.3V) : 16mA
 - Read current(1.8V) : 10mA
 - Write current(1.8V) : 15mA
 - Standby current(3.3V) : 700uA
 - Standby current(1.8V) : 600uA
- Data Byte Control(x16 I/O Mode)
 - LB : DQ₇~DQ₀, UB : DQ₁₅~DQ₈
- Memory cell : STT-MRAM
 - nonvolatile
- Density
 - 32Mb
- Data Integrity : No external ECC required
- Data Endurance
 - Unlimited read cycle
 - 10¹⁴ write cycles
- Data Retention
 - 20 years at 85°C
- Single Power Supply Operation
 - S3R3216V1M: 2.70V~3.60V
 - S3R3216R1M: 1.71V~1.98V
- Operating Temperature Range
 - Industrial Temperature : -40°C to 85°C
- RoHS compliant packages
 - 48FBGA (6 mm x 8 mm)
 - 54TSOP2 (10 mm x 22 mm)

Performance

Operation	Symbol	Typical Values		Units
		1.8V (S3R3216R1M)	3.3V (S3R3216V1M)	
Interpage Read Cycle Time	t _{RC}	70(Min.)		ns
Intrapage Read Cycle Time	t _{PRC}	15(Min.)		ns
Interpage Write Cycle Time	t _{WC}	240(Min.)		ns
Intrapage Write Cycle Time	t _{PWC}	15(Min.)		ns
Standby Current	I _{SB}	600	700	uA
Interpage Read Current	I _{CCR}	10	14	mA
Intrapage Read Current	I _{CCRP}	10	14	mA
Interpage Write Current	I _{CCW}	15	16	mA
Intrapage Write Current	I _{CCWP}	15	16	mA

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General Description

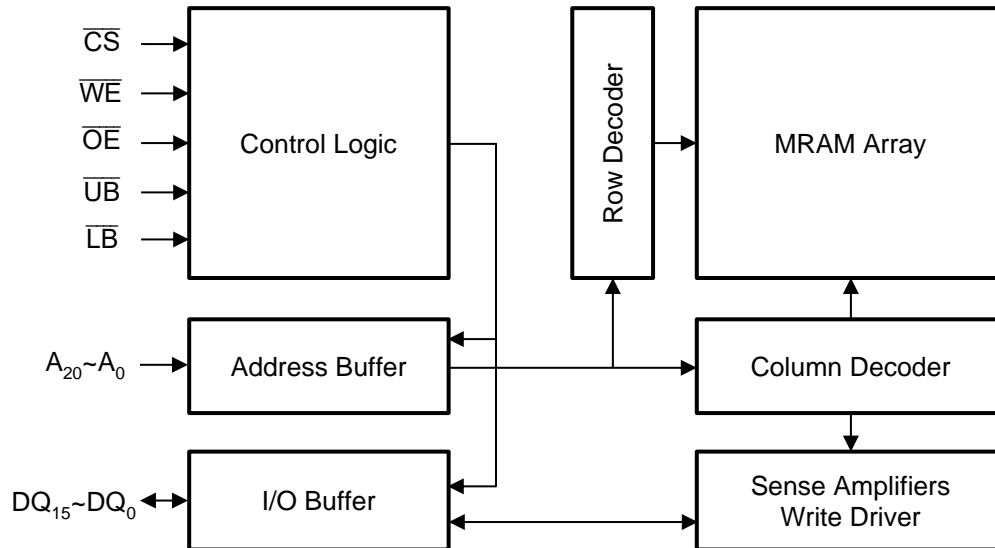
The device is a Spin-Transfer-Torque Magneto-resistive Random Access Memory (STT-MRAM). Data is always non-volatile and the device can replace FRAM, low-power SRAM or nvSRAM with same functionality and help to simplify system design. Due to the non-volatility and virtually unlimited endurance characteristics of STT-MRAM, it is suited for code storage, data logging, backup memory and working memory in industrial designs.

It is a fully random-access memory with parallel asynchronous interface. And x16 I/O mode allows that lower and upper byte access by data byte control (\overline{LB} , \overline{UB}).

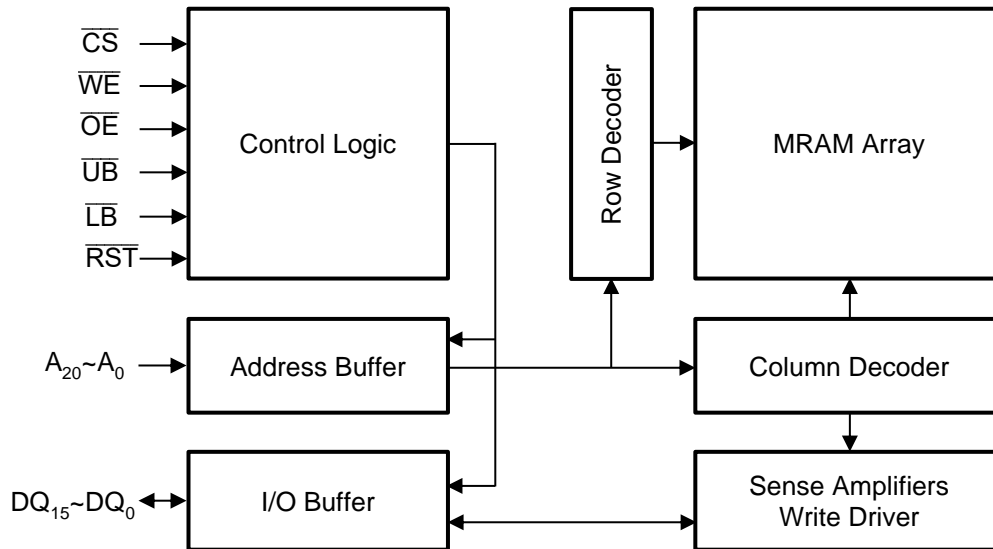
It supports the asynchronous page mode function to enhance the read and write performance. The page size is 4 words.

The S3R3216(V/R)1M is packaged in industrial standard 54TSOP2 and 48FBGA. These packages are compatible with similar low-power volatile and non-volatile products.

The device is offered with industrial (-40°C to 85°C) operating temperature range.

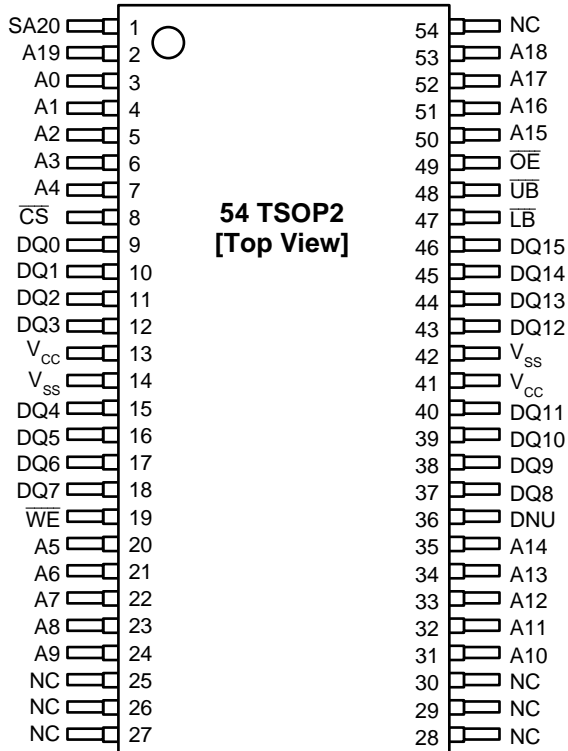
Pin Description – 3.3V Device
Figure 1 : Functional Block Diagram – 3.3V Device

Table 1 : Pin Description – 3.3V Device

Pin	Type	Description
\overline{CS}	Input	Chip Select: When \overline{CS} is driven Low, read or write operation are initiated. When \overline{CS} is driven High, the device enters standby mode, and all other input pins are ignored and the output pins are tri-stated. \overline{CS} should be High at power-up to prevent abnormal write operation. This pin does not have internal pullup resistor.
\overline{WE}	Input	Write Enable: When \overline{CS} and \overline{WE} are driven Low, write operation is initiated. The rising edge of \overline{CS} causes the device to transfer the data to memory array. The rising edge of \overline{WE} latches the input data. And, the falling edge of \overline{WE} latches a new page address for write cycles.
\overline{OE}	Input	Output Enable
\overline{LB}	Input	Lower Byte Control: DQ ₇ ~DQ ₀
\overline{UB}	Input	Upper Byte Control: DQ ₁₅ ~DQ ₈
A ₂₀ ~A ₀	Input	Address The LSB address A ₁ ~A ₀ are used for page mode read and write operation.
DQ ₁₅ ~DQ ₀	Bidirectional	Data Input/Outputs
V _{cc}	Supply	Power pin
V _{ss}	Supply	Ground pin
NC	-	Not Connected
DNU	-	Do Not Use : DNU's must be left unconnected.

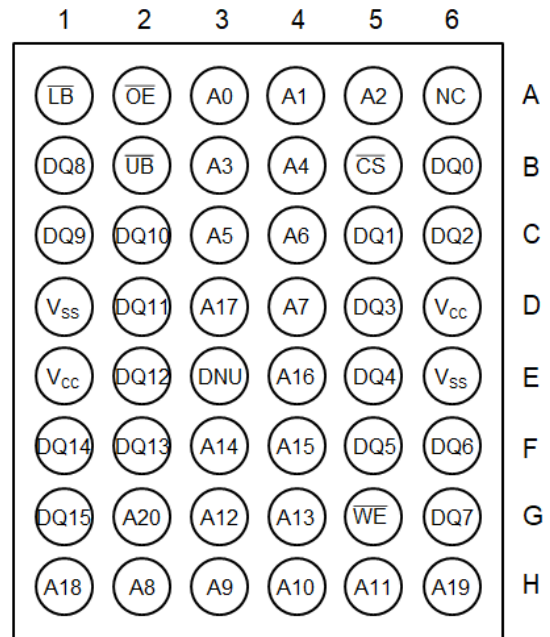
Pin Description – 1.8V Device
Figure 2 : Functional Block Diagram – 1.8V Device

Table 2 : Pin Description – 1.8V Device

Pin	Type	Description
\overline{CS}	Input	Chip Select: When \overline{CS} is driven Low, read or write operation are initiated. When \overline{CS} is driven High, the device enters standby mode, and all other input pins are ignored and the output pins are tri-stated. \overline{CS} should be High at power-up to prevent abnormal write operation. This pin does not have internal pullup resistor.
\overline{WE}	Input	Write Enable: When \overline{CS} and \overline{WE} are driven Low, write operation is initiated. The rising edge of \overline{CS} causes the device to transfer the data to memory array. The rising edge of \overline{WE} latches the input data. And, the falling edge of \overline{WE} latches a new page address for write cycles.
\overline{OE}	Input	Output Enable
\overline{LB}	Input	Lower Byte Control: DQ ₇ ~DQ ₀
\overline{UB}	Input	Upper Byte Control: DQ ₁₅ ~DQ ₈
A ₂₀ ~A ₀	Input	Address The LSB address A ₁ ~A ₀ are used for page mode read and write operation.
DQ ₁₅ ~DQ ₀	Bidirectional	Data Input/Outputs
\overline{RST}	Input	Reset \overline{RST} pin is a hardware RESET signal. When \overline{RST} is driven High, the device is in the normal operation mode. When \overline{RST} is driven Low, the device enters in the initialization mode. This pin has an internal pullup resistor.
V _{cc}	Supply	Power pin
V _{ss}	Supply	Ground pin
NC	-	Not Connected
DNU	-	Do Not Use : DNUs must be left unconnected.

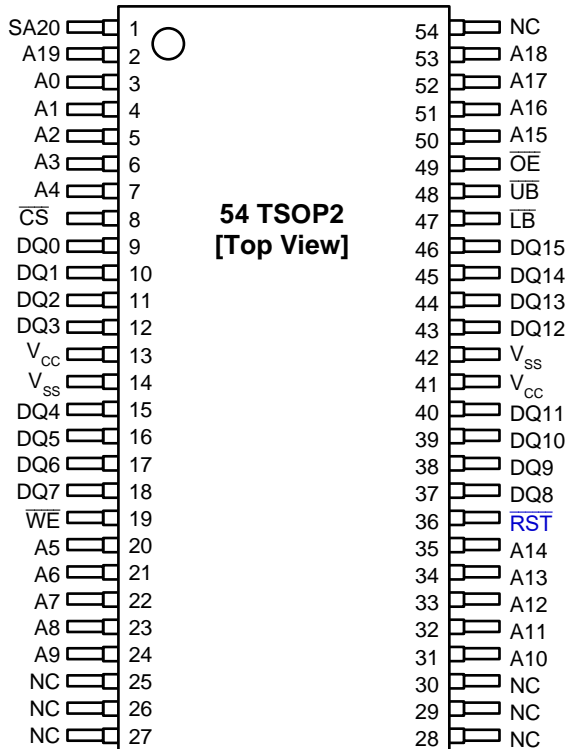
Package Pin Configuration – 3.3V Device



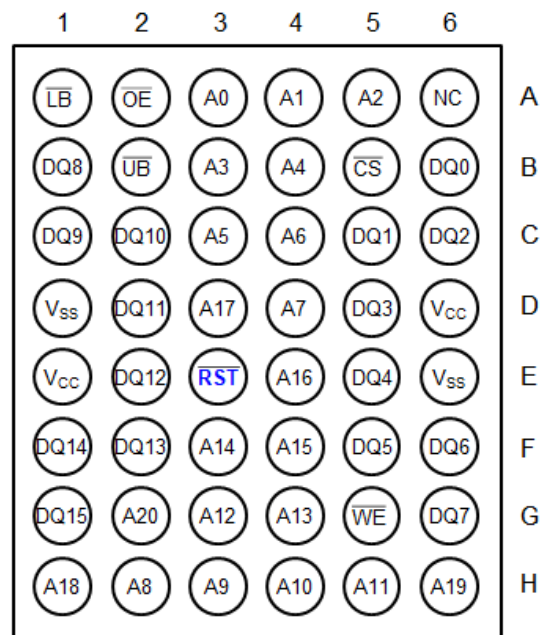
48 Ball FBGA (x16) [Top View]



Package Pin Configuration – 1.8V Device



48 Ball FBGA (x16) [Top view]



Functional Description

Functional Description – x16 I/O Mode

Table 3 : Functional Description - x16 I/O mode

CS	WE	OE	LB	UB	DQ ₇ ~DQ ₀	DQ ₁₅ ~DQ ₈	Modes	Supply Current
H	X	X	X	X	High-Z	High-Z	Not Selected	I _{SB}
L	H	H	X	X	High-Z	High-Z	Output disable	I _{CCR}
L	H	L	H	H	High-Z	High-Z	Output disable	I _{CCR}
L	H	L	L	H	Dout	High-Z	Lower Byte Read	I _{CCR}
L	H	L	H	L	High-Z	Dout	Upper Byte Read	I _{CCR}
L	H	L	L	L	Dout	Dout	Word Read	I _{CCR}
L	L	X	H	H	High-Z	High-Z	Input disable	I _{CCW}
L	L	X	L	H	Din	High-Z	Lower Byte Write	I _{CCW}
L	L	X	H	L	High-Z	Din	Upper Byte Write	I _{CCW}
L	L	X	L	L	Din	Din	Word Write	I _{CCW}

Address Pin

Table 4 : Address Pin

Density	Address Pin	Page Address Pin
32Mb	A ₂₀ ~A ₀	A ₁ ~A ₀

Electrical Specifications

Absolute Maximum Ratings

Stresses greater than those listed may cause permanent damage to the device. This is a stress rating only. Exposure to maximum rating for extended periods may adversely affect reliability.

Table 5 : Absolute Maximum Ratings

Parameter	Min.	Max.	Units
Voltage on Vcc Supply Relative to VSS: 3.3V Device	-0.5	3.8	V
Voltage on Any Pin relative to VSS : 3.3V Device	-0.5	3.8	V
Voltage on Vcc Supply Relative to VSS: 1.8V Device	-0.5	2.35	V
Voltage on Any Pin relative to VSS : 1.8V Device	-0.5	2.35	V
Storage Temperature	-55	150	°C
Operating Ambient Temperature	-40	85	°C
ESD HBM (Human Body Model)	≥ 2000 V		V
ESD CDM (Charged Device Model)	≥ 500 V		V
Solder Reflow Process	JEDEC J-STD-020 reflow profiles - Peak temperature ≤ 260°C - The time above 255°C ≤ 30 seconds - Reflow cycles ≤ 3 times		

Endurance, Retention and Magnetic Immunity

Table 6 : Endurance, Retention and Magnetic Immunity

Parameter	Conditions	Min.	Max.	Units
Write Endurance	-25°C	10 ¹⁴	-	Cycles/page
Data Retention	85°C	20	-	years
Magnetic Field During Write or Read	-	-	24,000	A/m

Recommended Operating Conditions

Table 7 : Recommended Operating Conditions

Parameter / Condition	Min.	Typ.	Max.	Units
Operating Temperature	-40	25	85	°C
Vcc Supply Voltage : 3.3V Device	2.7	3.3	3.6	V
Vcc Supply Voltage : 1.8V Device	1.71	1.8	1.98	V
Vss Supply Voltage	0.0	0.0	0.0	V

Pin Capacitance

Table 8 : Pin Capacitance

Parameter	Conditions	Typ.	Max.	Units
Input Pin Capacitance	TEMP = 25°C; f = 1 MHz; $V_{IN} = 0V$	-	4	pF
Input/Output Pin Capacitance	TEMP = 25°C; f = 1 MHz; $V_{IO} = 0V$	-	6	pF

* Capacitance is sampled and not 100% tested

AC Test Condition

Table 9 : AC Test Conditions

Parameter	Value
Input pulse levels	0.0V to V_{CC}
Input rise and fall times	1ns/1V
Input and output measurement timing levels	$V_{CC}/2$
Output Load	CL = 30pF

DC Characteristics

Table 10 : DC Characteristics : 3.3V Device

Parameters	Symbol	Test Conditions	Min	Typ	Max	Unit	
Input Leakage Current	I_{LI}	$V_{IN} = V_{SS} \text{ to } V_{CC}$	-2	-	+2	uA	
Output Leakage Current	I_{LO}	$\overline{CS}=V_{IH} \text{ or } \overline{OE}=V_{IH} \text{ or } \overline{WE}=V_{IL}$ $V_{OUT} = V_{SS} \text{ to } V_{CC}$	-2	-	+2	uA	
Read Current	Random	I_{CCR}	$V_{CC} \text{ (max)}, I_{OUT}=0\text{mA}$	-	14	18	mA
	Page mode	I_{CCRP}	$V_{CC} \text{ (max)}, I_{OUT}=0\text{mA}$	-	14	18	mA
Write Current	Random	I_{CCW}	$V_{CC} \text{ (max)}$	-	16	20	mA
	Page mode	I_{CCWP}	$V_{CC} \text{ (max)}$	-	16	20	mA
Standby Current	I_{SB}	$V_{CC} \text{ (max)}, \overline{CS} \geq V_{CC}-0.2\text{V}$	-	700	950	uA	
Input High Voltage	V_{IH}	-	$0.7 \times V_{CC}$	-	$V_{CC}+0.3$	V	
Input Low Voltage	V_{IL}	-	-0.3	-	$0.2 \times V_{CC}$	V	
Output High Voltage	V_{OH}	$I_{OH}=-1\text{mA}$	2.4	-	-	V	
Output Low Voltage	V_{OL}	$I_{OL}=2\text{mA}$	-	-	0.4	V	

Table 11 : DC Characteristics : 1.8V Device

Parameters	Symbol	Test Conditions	Min	Typ	Max	Unit	
Input Leakage Current	I_{LI}	$V_{IN} = V_{SS} \text{ to } V_{CC}$	-2	-	+2	uA	
Output Leakage Current	I_{LO}	$\overline{CS}=V_{IH} \text{ or } \overline{OE}=V_{IH} \text{ or } \overline{WE}=V_{IL}$ $V_{OUT} = V_{SS} \text{ to } V_{CC}$	-2	-	+2	uA	
Read Current	Random	I_{CCR}	$V_{CC} \text{ (max)}, I_{OUT}=0\text{mA}$	-	10	14	mA
	Page mode	I_{CCRP}	$V_{CC} \text{ (max)}, I_{OUT}=0\text{mA}$	-	10	14	mA
Write Current	Random	I_{CCW}	$V_{CC} \text{ (max)}$	-	15	19	mA
	Page mode	I_{CCWP}	$V_{CC} \text{ (max)}$	-	15	19	mA
Standby Current	I_{SB}	$V_{CC} \text{ (max)}, \overline{CS} \geq V_{CC}-0.2\text{V}$	-	600	900	uA	
Input High Voltage	V_{IH}	-	$0.7 \times V_{CC}$	-	$V_{CC}+0.3$	V	
Input Low Voltage	V_{IL}	-	-0.3	-	$0.3 \times V_{CC}$	V	
Output High Voltage	V_{OH}	$I_{OH}=-1\text{mA}$	1.4	-	-	V	
Output Low Voltage	V_{OL}	$I_{OL}=2\text{mA}$	-	-	0.4	V	

AC Timing Parameters

Table 12 : Read AC Timing Parameter

Parameter	Symbol	Min.	Max.	Units
Read Cycle Time (Interpage)	t _{RC}	70	-	ns
Page Read Cycle Time (Intrapage)	t _{PRC}	15	-	ns
$\overline{\text{CS}}$ Read Active Time	t _{RCA}	65	-	ns
$\overline{\text{CS}}$ Falling to Valid Output Time	t _{CO}	-	65	ns
Address Access Time ²⁾	t _{AA}	-	80	ns
Page Address Access Time	t _{PAA}	-	15	ns
$\overline{\text{CS}}$ Rising to Output Hold Time	t _{COH}	3	-	ns
Address change to Output Hold Time ²⁾	t _{OH}	30	-	ns
Page address change to Output Hold Time	t _{POH}	5	-	ns
$\overline{\text{OE}}$ Falling to Valid Output Time	t _{OE}	-	15	ns
$\overline{\text{UB}}, \overline{\text{LB}}$ Falling to Valid Output Time ¹⁾	t _{BA}	-	15	ns
$\overline{\text{CS}}$ Rising to High-Z Output Time	t _{CHZ}	-	8	ns
$\overline{\text{OE}}$ Rising to High-Z Output Time	t _{OHZ}	-	8	ns
$\overline{\text{UB}}, \overline{\text{LB}}$ Rising to High-Z Output Time ¹⁾	t _{BHZ}	-	8	ns
Address Transition to $\overline{\text{CS}}$ falling Time ²⁾	t _{CAS}	0	-	ns
$\overline{\text{CS}}$ Rising to Address Transition Time ²⁾	t _{CAH}	0	-	ns
$\overline{\text{WE}}$ Rising to $\overline{\text{CS}}$ Falling Time	t _{WES}	0	-	ns
$\overline{\text{CS}}$ Rising to $\overline{\text{WE}}$ Falling Time	t _{WEH}	0	-	ns
$\overline{\text{CS}}$ High Time for Read End	t _{CSDR}	5	-	ns
Address Transition Interval Time	t _{AX}	-	5	ns

Notes:

1. Those parameters are applied for x16 I/O mode only.
2. Address except for page address

AC Timing Parameters

Table 13 : Write AC Timing Parameter

Parameters	Symbol	Min	Max	Unit
Write Cycle Time (Interpage)	t _{WC}	240	-	ns
$\overline{\text{CS}}$ Write Active Time ³⁾	t _{WCA}	20	-	ns
$\overline{\text{CS}}$ Falling to End of Write Time	t _{CW}	20	-	ns
Page Write Cycle Time (Intrapage)	t _{PWC}	15	-	ns
$\overline{\text{WE}}$ Falling to End of Write (invalid output does not appear)	t _{WP}	10	-	ns
$\overline{\text{WE}}$ Falling to End of Write (invalid output appears)	t _{WP1}	20	-	ns
$\overline{\text{UB}}$, $\overline{\text{LB}}$ Falling to End of Write Time ¹⁾	t _{BW}	10	-	ns
$\overline{\text{WE}}$ Falling to Output High-Z Time	t _{WHZ}	-	8	ns
Valid Input Data to End of Write Time	t _{DS}	8	-	ns
End of Write to Valid Input Data Time	t _{DH}	0	-	ns
Address Transition Time to $\overline{\text{CS}}$ falling ²⁾	t _{CAS}	0	-	ns
$\overline{\text{CS}}$ Rising to Address Transition Time ²⁾	t _{CAH}	0	-	ns
Page Address Transition to $\overline{\text{WE}}$ falling Time	t _{PAS}	0	-	ns
$\overline{\text{WE}}$ falling to Page Address Transition Time	t _{PAH}	10	-	ns
$\overline{\text{WE}}$ High Time for Page Write	t _{PWH}	3	-	ns
$\overline{\text{CS}}$ High Time for Write End ³⁾	t _{CSDW}	180	-	ns

Notes:

1. Those parameters are applied for x16 I/O mode only.
2. Address except for page address
3. t_{WCA} + t_{CSDW} ≥ t_{WC}

Power On/Off Sequence : 3.3V Device

- When power-up, power-down or power-loss, \overline{CS} must follow V_{cc} to provide data protection.
- It is recommended that \overline{CS} must follow V_{cc} when V_{cc} is below $V_{cc}(\text{minimum})$ and during t_{PU} .
- A 10K Ω pull-up resistor between V_{cc} and \overline{CS} pin is recommended.
- Normal operation must start after t_{PU} .

Figure 3 : Power-Up/Down Behavior

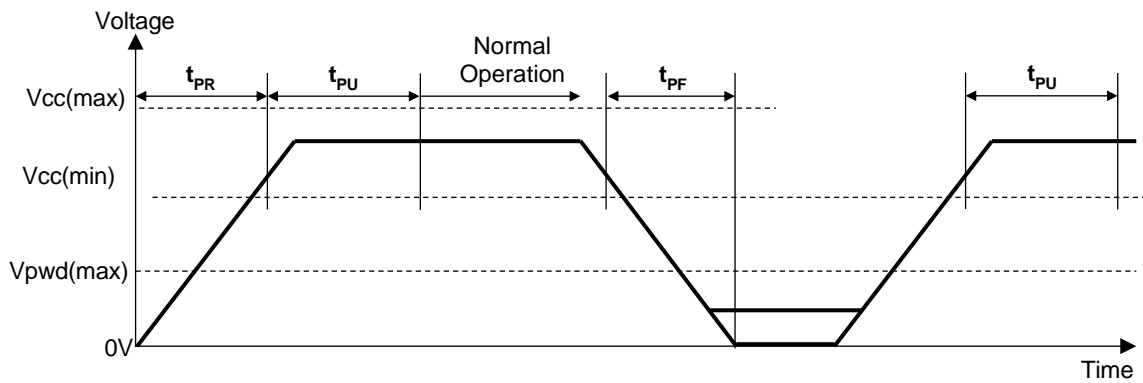


Table 14 : Power-Up/Down Timing

Parameter	Symbol	Min	Max	Units
Vcc Range	V_{CC}	2.7	3.6	V
Vcc rising time	$t_{PR}^{(1)}$	30	-	$\mu\text{s}/V$
Vcc falling time	$t_{PF}^{(1)}$	30	-	$\mu\text{s}/V$
Vcc(min) to \overline{CS} Low (first instruction) time	$t_{PU}^{(1)}$	2.0	-	ms
Vcc needed to below V_{pwd} for ensuring initialization will occur	$V_{PVD}^{(1)}$	-	1.6	V

Notes:

1: These parameters are guaranteed by characterization; not tested in production.

Power On/Off Sequence : 1.8V Device

- When power-up, power-down or power-loss, \overline{CS} must follow V_{cc} to provide data protection.
- It is recommended that \overline{CS} must follow V_{cc} when V_{cc} is below $V_{cc}(\text{minimum})$ and during t_{PU} .
- A 10K Ω pull-up resistor between V_{cc} and \overline{CS} pin is recommended.
- Normal operation must start after t_{PU} .
- Normal operation must start after t_{RST} .

Figure 4 : Power-Up/Down Behavior

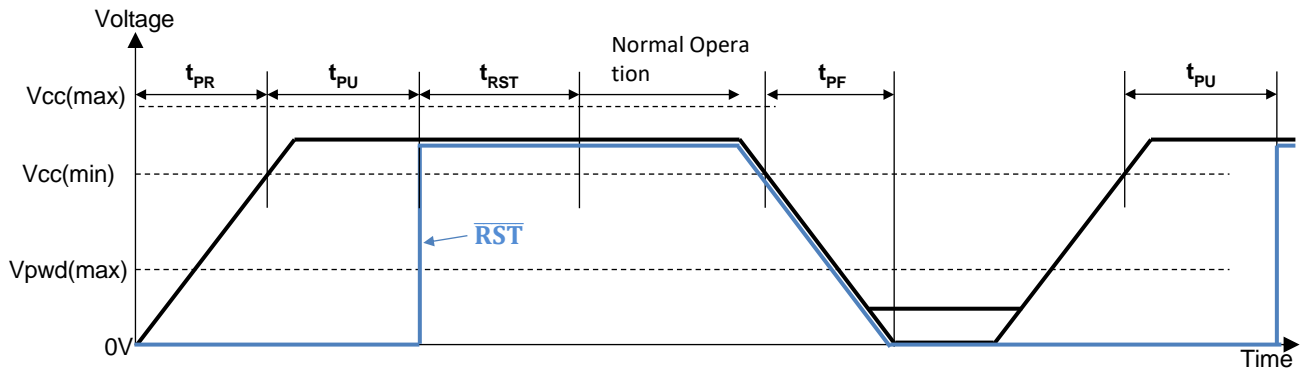


Table 15 : Power-Up/Down Timing

Parameter	Symbol	Min	Max	Units
Vcc Range	Vcc	1.71	1.98	V
Vcc rising time	$t_{PR}^{(1)}$	30	-	$\mu\text{s/V}$
Vcc falling time	$t_{PF}^{(1)}$	30	-	$\mu\text{s/V}$
Vcc(min) to \overline{RST} Low time	$t_{PU}^{(1)}$	1.0	-	ms
\overline{RST} High to \overline{CS} Low (first instruction) time	$t_{RST}^{(1)}$	2.0	-	ms
Vcc needed to below V_{pvd} for ensuring initialization will occur	$V_{PWD}^{(1)}$	-	0.8	V
Reset Time	$t_{RST}^{(1)}$	2.0	-	ms

Notes:

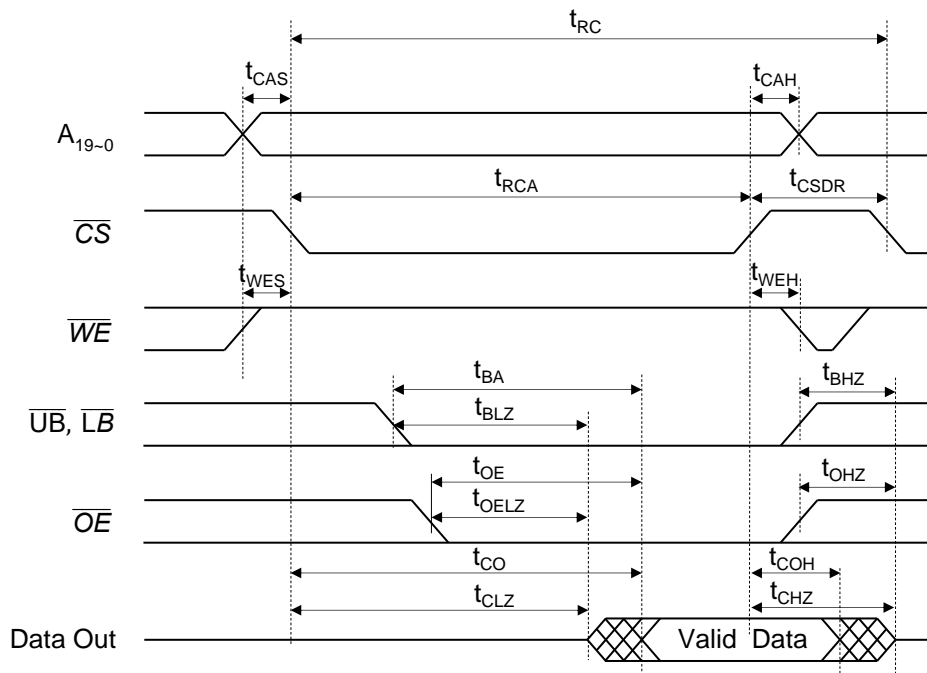
1: These parameters are guaranteed by characterization; not tested in production.

Device Operation

Read Operation : Interpage

Read operation is initiated when \overline{CS} goes to low and \overline{WE} is high. The falling edge of \overline{CS} latches the address and starts to read data from memory array. The output data are available after t_{CO} . The minimum random read cycle time is t_{RC} . The data remains in High-Z until the valid data is output.

Figure 5 : Timing Waveform of Read Cycle : x16 I/O mode



Page Mode Read Operation : Intrapage

The device supports the page mode read function to enhance the read performance. It reads a page data from memory array and latches the data into an internal page buffer.

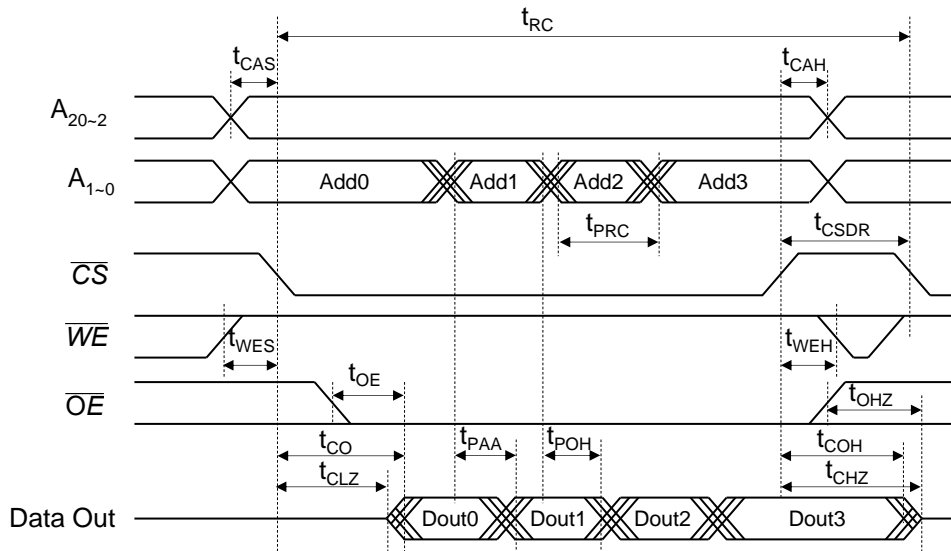
The first data is output after t_{CO} . When the next page address is input, subsequent data is output from the page buffer after t_{PAA} .

The sequence and length of page address are not restricted.

For example, the sequence A2-A0-A1 is available.

Parameter	x16 I/O mode
Page Address	A ₁ ~A ₀
Page size	4-word (8-bytes)

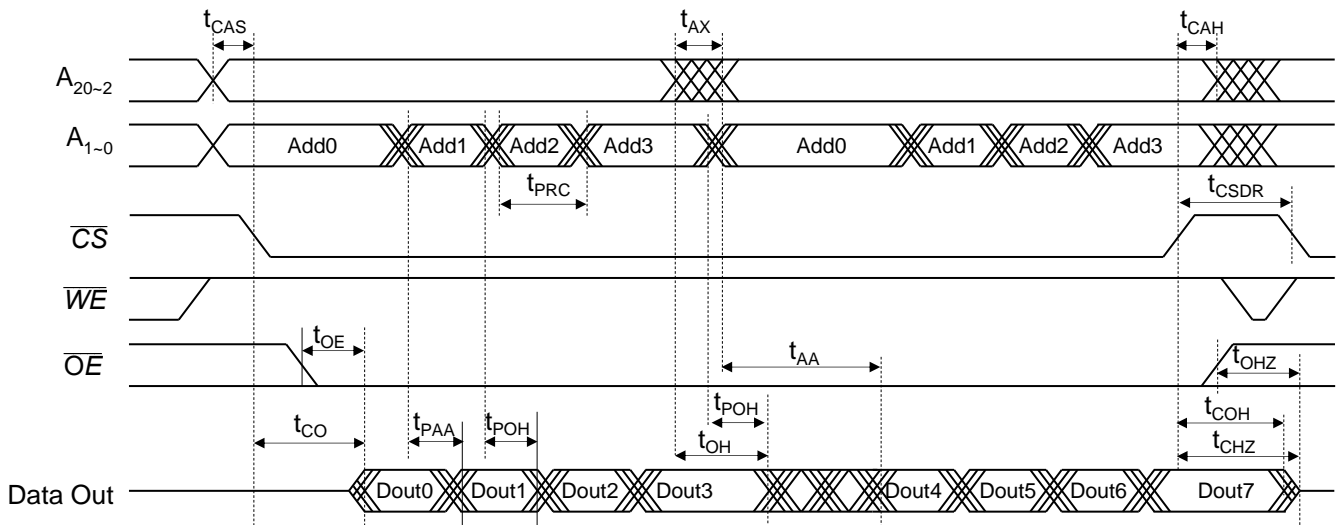
Figure 6 : Timing Waveform of Page Mode Read Cycle : x16 I/O mode



Address Access Read Operation

During \overline{CS} is low and \overline{WE} is high, if a random address (except for the page address) are changed, the device reads a page data from memory array of a new address and latches the data into an internal page buffer. The first data is output after t_{AA} . When the next page address is input, subsequent data is output from the page buffer after t_{PAA} . The random address transition time should not exceed t_{AX} .

Figure 7 : Timing Waveform of Address Access Read Cycle : x16 I/O mode

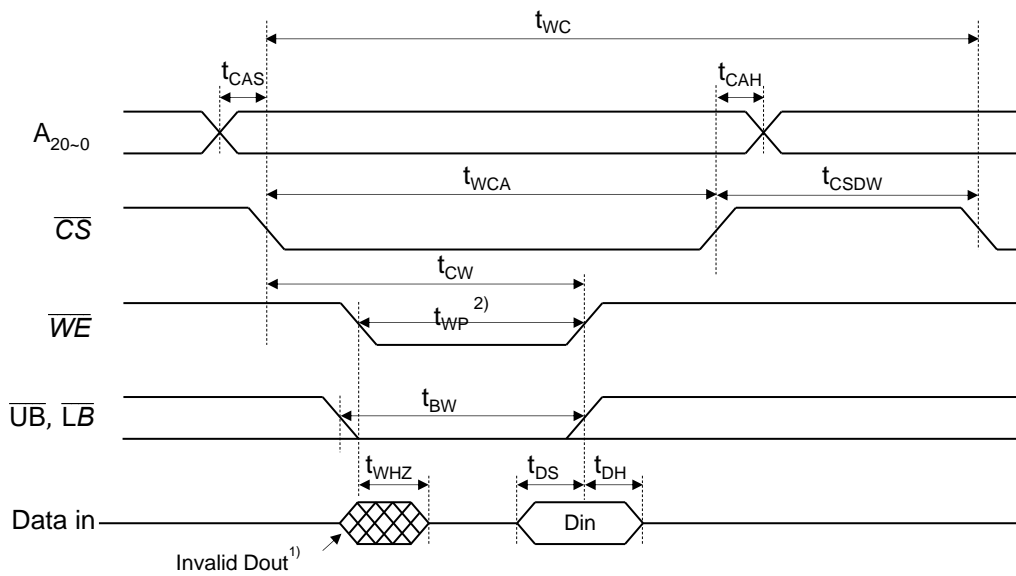


Write Operation (\overline{WE} control) : Interpage

Write operation is initiated when \overline{WE} goes to low and \overline{CS} is low. The device latches address on the falling edge of \overline{CS} . It latches the lower byte data on the rising edge of \overline{WE} or \overline{LB} and the upper byte data on the rising edge of \overline{WE} or \overline{UB} for x16 I/O mode.

The rising edge of \overline{CS} causes the device to transfer the input data to memory array.

Figure 8 : Timing Waveform of Write Cycle (\overline{WE} control) : x16 I/O mode



Notes :

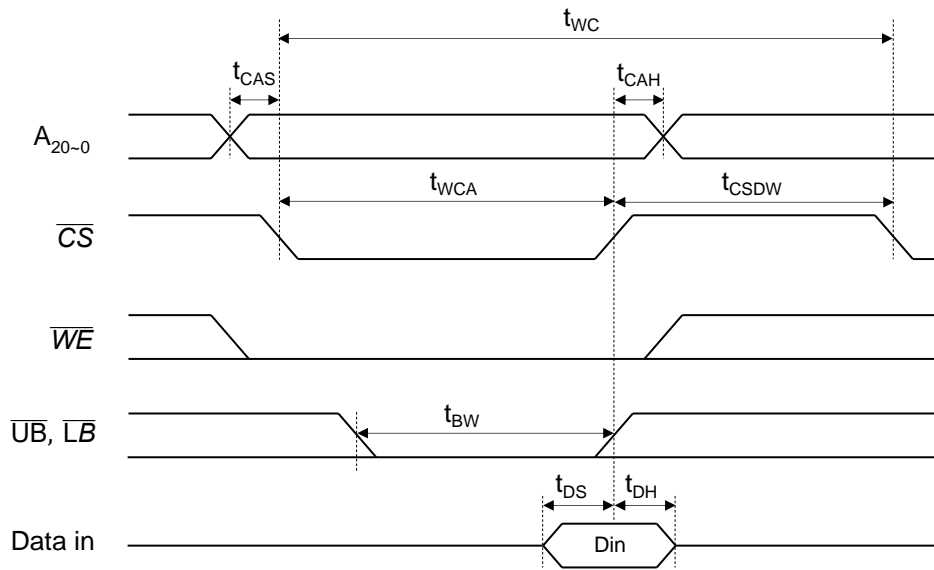
1. The data pins remain in High-Z state if the time of \overline{CS} falling to \overline{WE} falling is smaller than 30ns or \overline{OE} is High.
2. In case that the data pins do not remains in High-Z state, t_{WP} should be t_{WP1}
3. $t_{WCA} + t_{CSDW} \geq t_{WC}$

Write Operation (\overline{CS} control) : Interpage

Write operation is initiated when \overline{CS} goes to low and \overline{WE} is low. The device latches address on the falling edge of \overline{CS} . It latches the lower byte data on the rising edge of \overline{CS} or \overline{LB} and the upper byte data on the rising edge of \overline{CS} or \overline{UB} for x16 I/O mode.

The rising edge of \overline{CS} causes the device to transfer the input data to memory array.

Figure 9 : Timing Waveform of Write Cycle (\overline{CS} control) : x16 I/O mode



Page Mode Write Operation : Intrapage

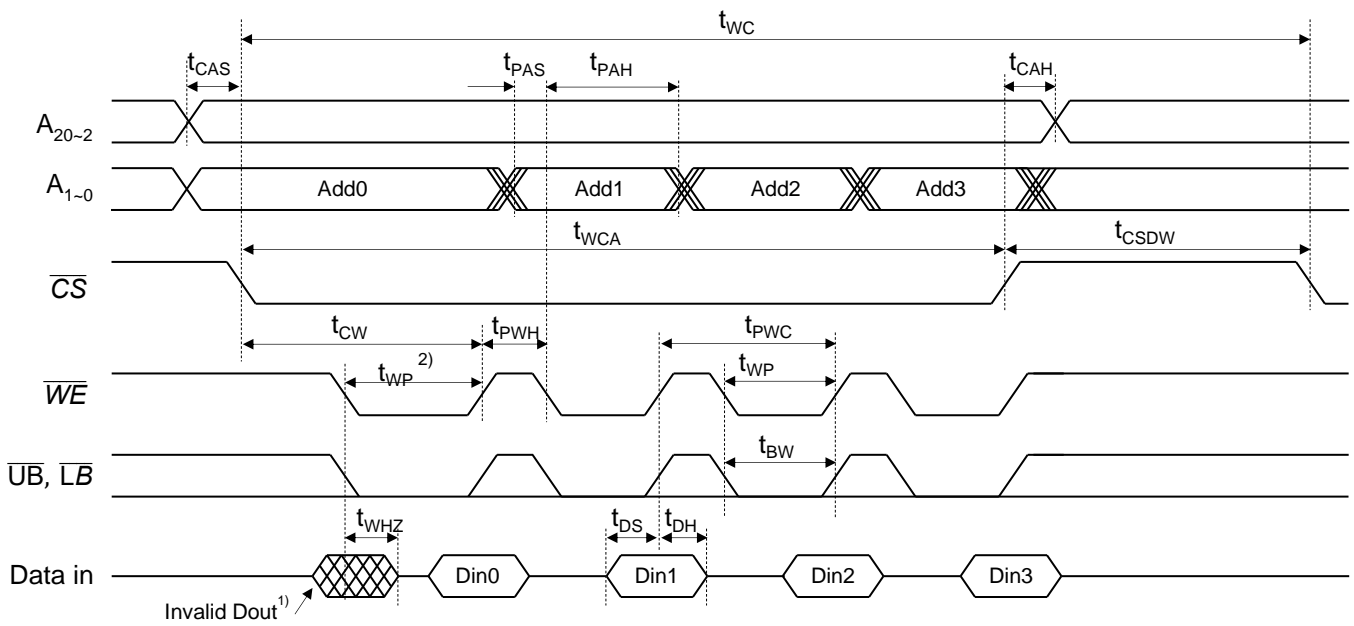
The device supports the page mode write function to enhance the write performance. It latches a page address every falling edge of \overline{WE} .

It latches the lower byte data on every rising edge of \overline{WE} or \overline{LB} and the upper byte data on every rising edge of \overline{WE} or \overline{UB} for x16 I/O mode.

The rising edge of \overline{CS} causes the device to transfer the input data to memory array.

The sequence and length of page address are not restricted. For example, the sequence A2-A0-A1 is available.

Figure 10 : Timing Waveform of Page Mode Write Cycle : x16 I/O Mode



Thermal Resistance

Table 16 : Thermal Resistance

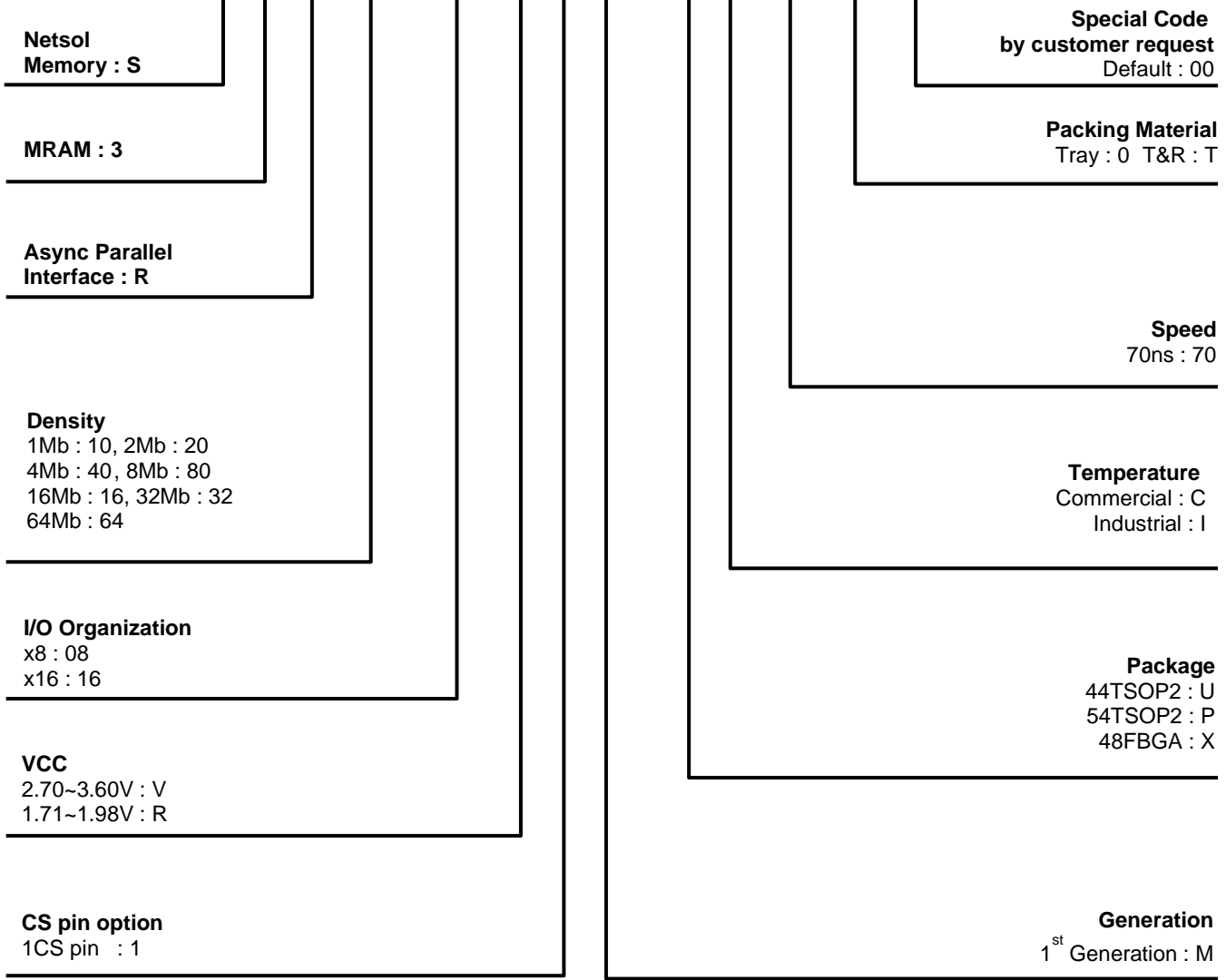
Parameter	Description	48FBGA	54TSOP2	Unit
θ_{JA}	Thermal resistance (junction to ambient)	69.4	50.3	°C/W
θ_{JC}	Thermal resistance (junction to case)	31.1	14.4	

Notes:

1: These parameters are guaranteed by characterization; not tested in production

Part Numbering System

S	3	R	X	X	X	X	X	X	X	X	-	X	X	X	X	X	X
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18



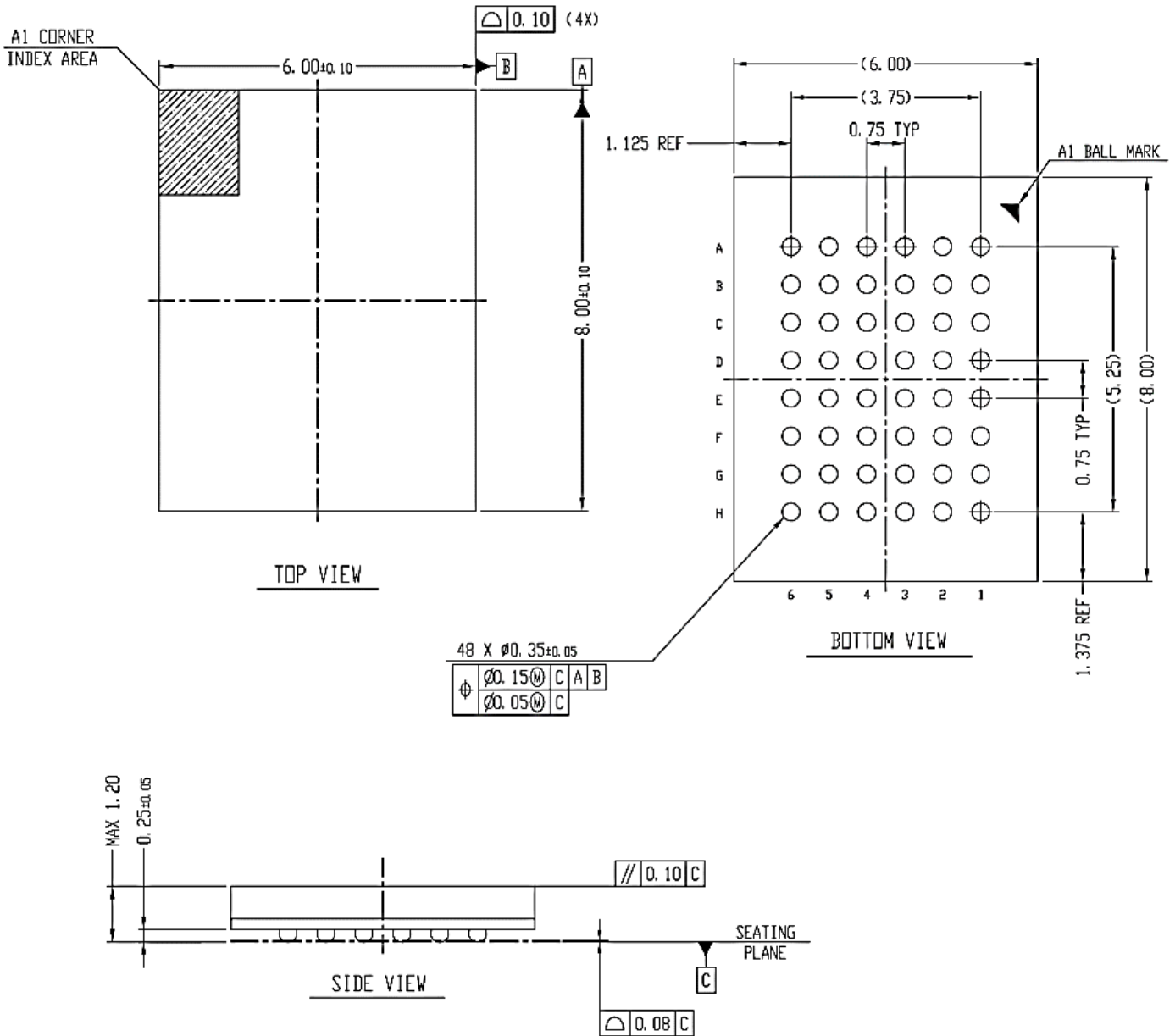
Ordering Part Numbers

Table 18 : Ordering Part Numbers

Density	Voltage	Temperature	Package	Packing Material	Part Number
32Mb	3.3V	-40°C ~ 85°C	54TSOP2	Tray	S3R3216V1M-PI70
				Tape and Reel	S3R3216V1M-PI70T
			48FBGA	Tray	S3R3216V1M-XI70
				Tape and Reel	S3R3216V1M-XI70T
	1.8V	-40°C ~ 85°C	54TSOP2	Tray	S3R3216R1M-PI70
				Tape and Reel	S3R3216R1M-PI70T
			48FBGA	Tray	S3R3216R1M-XI70
				Tape and Reel	S3R3216R1M-XI70T

Package Dimension

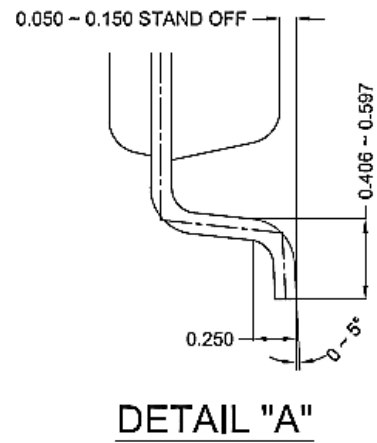
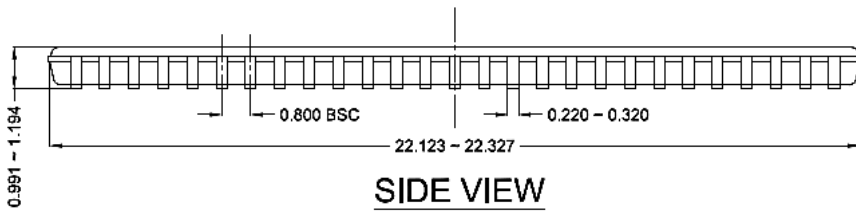
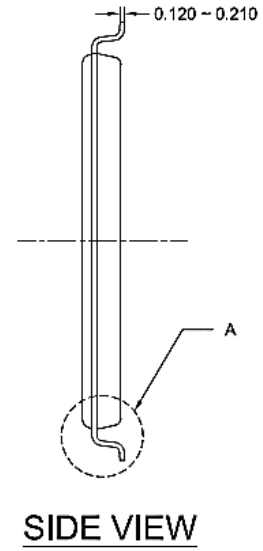
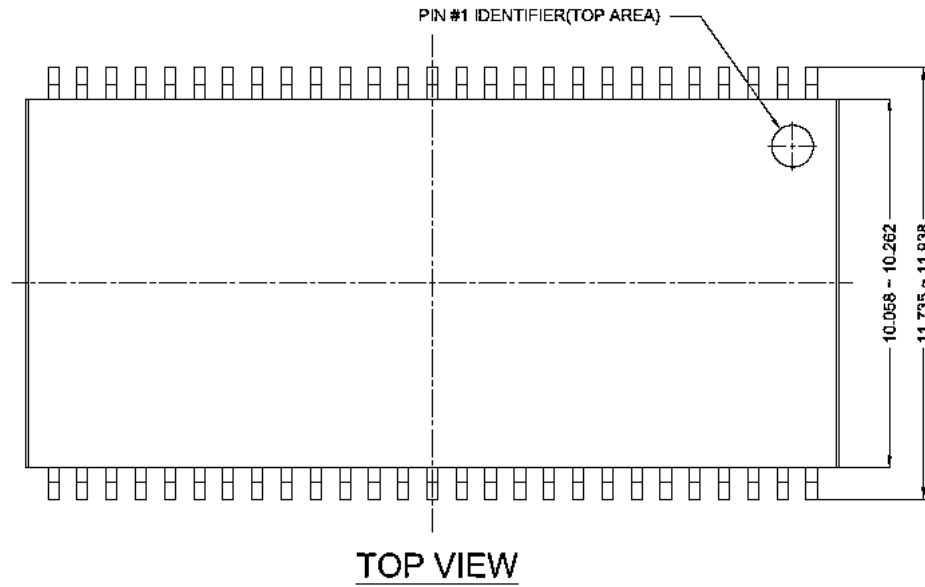
48 FBGA



[Notes]

1. All Dimensions in Millimeters
2. Solder ball Diameter is post reflow diameter
(Raw Solder ball size is Φ0.30mm)

54 TSOP2



[Notes]

1. Dimensions in Millimeters
2. Lead Finish : Solder Plated
3. Package dimensions refer to JEDEC MS-024

Revision History

Revision	Date	Description
0.0	Feb, 2023	Initial Release, Preliminary
1.0	Jul, 2023	1. Remove Preliminary status 2. Update DC characteristics(Table 10,11)
1.1	Mar. 2024	1. Change Write Cycle Time (Table 13) - t _{wc} 320ns → 240ns, t _{c_{sdw}} 250ns → 180ns
1.2	Jan. 2025	1. Update the Data Retention parameter(Table 6)

* Products and specifications discussed herein are subject to change by Netsol without notice.